

Product Information Sheet

MATERIAL ID:

EPO-TEK® TJ1183-LH

Date: Sep 2013

Rev: VI

Material Description: A single component, low-halogen, electrically insulating die attach adhesive with extended pot life.

Number of Components: Single

Mix Ratio by Weight: N/A

Recommended Cure: 150°C/1 Hour

Specific Gravity: 1.52

Pot Life: 9 Days

Shelf Life: One year at -40°C

NOTE: Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before mixing and prior to use.

MATERIAL CHARACTERISTICS: To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/1 Hour

* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:	
* Color (before cure):	Light yellow
* Consistency	Smooth thixotropic paste
* Viscosity (23°C): @ 10 rpm	25,000-40,000 cPs
Thixotropic Index:	2.6
* Glass Transition Temp:	≥ 90 °C (Dynamic Cure: 20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)
Coefficient of Thermal Expansion (CTE):	
Below Tg:	47 x 10 ⁻⁶ in/in°C
Above Tg:	149 x 10 ⁻⁶ in/in°C
Shore D Hardness:	85
Lap Shear @ 23°C:	> 2,000 psi
Die Shear @ 23°C:	> 25 Kg 8,500 psi
Degradation Temp:	412 °C
Weight Loss:	
@ 200°C	0.05 %
@ 250°C	0.24 %
@ 300°C	0.66 %
Operating Temp:	
Continuous:	- 55°C to 250 °C
Intermittent:	- 55°C to 350°C
Storage Modulus:	901,074 psi
* Particle Size:	≤ 20 microns

ELECTRICAL AND THERMAL PROPERTIES:	
Thermal Conductivity:	0.38 W/mK
Volume Resistivity @ 23°C:	≥ 1 x 10 ¹³ Ohm-cm
Dielectric Constant (1KHz):	3.17
Dissipation Factor (1KHz):	0.010

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

EPOXY TECHNOLOGY, INC.

14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782

[WEB SITE: www.epotek.com](http://www.epotek.com)